



MATERIALS WIRES & FOILS

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Metallization Aluminum Wires

These pure Aluminum wires are used for metallization process in vacuum-coating equipments.

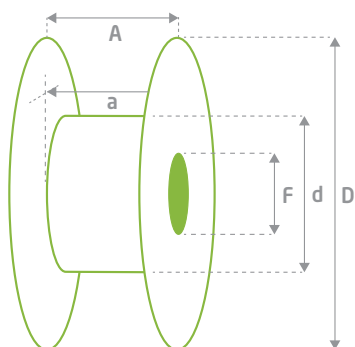
SPECIFICATIONS

Purity grades: from 99.5% to 99.99%
Wire diameters: from 1.00 mm to 3.00 mm

APPLICATIONS

- Flexible packagings
- Solar films
- Capacitors
- Holograms
- Head lights
- Reflective coatings (various applications)

Each spool is delivered with a specific certificate of analysis, and individually identified which guarantees the total traceability of the material.



Al wire on plastic spool

ORDERING INFORMATION

P/N (INVENTORY)	DIMENSIONS	PURITY
ALU1.0	Ø 1.0 mm ; 5 kg	99.99%
ALU1.2	Ø 1.2 mm ; 5 kg	99.99%
ALU1.5	Ø 1.5 mm ; 5 kg	99.99%
ALU1.57	Ø 1.57 mm ; 2 kg	99.8%
ALU2.0	Ø 2.00 mm ; 5 kg	99.99%

Other diameters and purities on request.

STANDARD SPOOL DIMENSIONS (mm)

D	d	F	A	a	CAPACITY
200	102	51	53	44	2.2 kg
250	125	18	78	68	5.2 kg

Wire Forming for Vacuum Metallization

Neyco provides Aluminum, Stainless Steel, Nickel/Chromium wire forming and other dedicated shapes for vacuum metallization.

Each lot of product is identified with a dedicated number, which guarantees the total traceability of the material. UHV Cleaning in our laboratory.

Shapes, dimensions and weights: upon request.



Protective Aluminum Rolls

Neyco provides high-quality Aluminum rolls dedicated to vacuum applications (UHV and secondary vacuum compatible).



P/N (INVENTORY)	DIMENSIONS	THICKNESS	PURITY
ROULALU	200 mm x 200 m	11 μm	99.5+%
ROULALU2	500 mm x 200 m	12 μm	99.5+%
ALLU100X30	100 mm x 200 m	30 μm	99.5+%
ROULALU-500x50	500 mm x 50 m	50 μm	99.5+%
ALU120x30	120 mm x 30 m	30 μm	99.5+%
ALU0.1X600X50	600 mm x 50 m	100 μm	99.5+%

Other thickness and dimensions available on request (even in small quantities).

Wires, Foils & Rods

Neyco provides high purity metals and metal alloys in wires, rods, plates and foils.

SOME EXAMPLES OF MATERIALS

Al, Ag, Au, Cr, Co, Cu, Hf, In, Fe, LaB_6 , Mg, Mo, Ni, Nb, Pb, Pt, Pd, Ta, Si, Sn, Ti, W, V, Zn, Zr, Stainless Steel 304L/316L/316LN...AISI...

PURITIES

99.8% to 99.999+%.

DIMENSIONS

- Thickness:
 - from 2 μm to 25 μm for ultrathin foils,
 - few μm to several mm for others.
- Other dimensions:
 - according to request.

All items are delivered with an analysis certificate.



Bonding Wires

Bonding wires are used for a wide range of products, such as integrated circuits (ICs and LSIs) and transistors. It connects Aluminum electrode and Lead electrode on semiconductor IC chip.

Our bonding wires are delivered with a specific certificate of analysis.

TANAKA ALUMINUM BONDING WIRES

AI BONDING WIRE

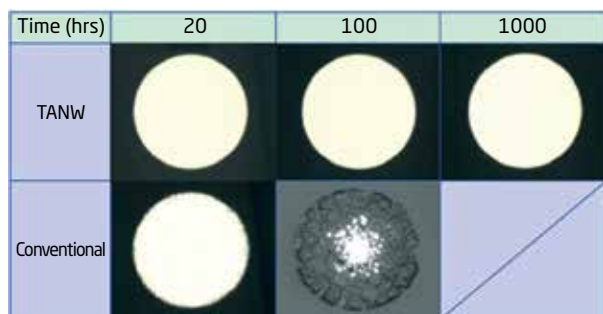
Features

- Excellent corrosion resistance under PCT (TANW type)
- Excellent bondability
- Hard, Soft-1, and Soft-2 are available according to applications.

Dimensions

Diameter from $100 \pm 5 \mu\text{m}$ to $500 \pm 10 \mu\text{m}$.

Cross section after PCT



Wire Dia.: $300 \mu\text{m}$ PCT: at 121°C , 100% RH, 2atm

Al 1%Si BONDING WIRE

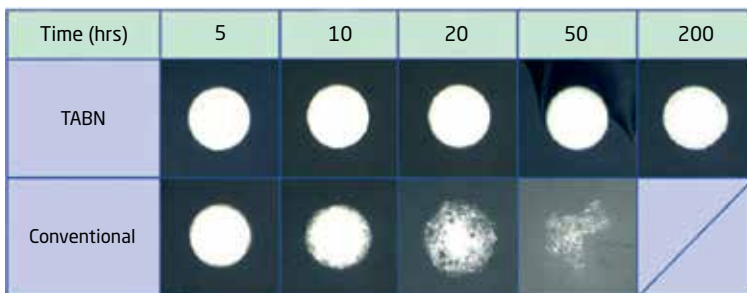
Features

- Uniform Si distribution
- Stable mechanical properties
- Stable quality wire without any curl, dirt and surface flaws
- Excellent bondability
- Excellent corrosion resistance under PCT (TABN type)

Dimensions

Diameter from $18 \pm 1 \mu\text{m}$ to $80 \pm 3 \mu\text{m}$.

Cross section after PCT



Wire Dia.: $30 \mu\text{m}$ PCT: at 121°C , 100% RH, 2atm

Al ALLOY BONDING WIRE

Features

- 99% purity Al alloy
- Finer grain size & higher tensile strength
- Excellent heat resistance
- Excellent thermal fatigue resistance

Dimensions

Diameter from $100 \mu\text{m}$ to $500 \mu\text{m}$.

TANAKA GOLD BONDING WIRES

Au BONDING WIRE

Features

- Stable stitch bond (1st and 2nd bondings)
- Excellent performance in thermal stress environment
- Fine pitch bonding
- Excellent bonding
- Good for fine pitch small pads
- High strength with less wire sweep
- Less neck damage, good for fine pitch pads
- Super low loops (long & short)

Dimensions

Diameter from 15 ±1 μm to 38 ±1 μm.



Gold bonding wire spool

Au ALLOY BONDING WIRE

Features

- Higher bond reliability on halogen compound (GPG series)
- Good squashed ball shape (GPG -2)
- Continuous wire bond stability (GPG-3)

Dimensions

Diameter from 15 μm to 30 μm.

Au BUMPING WIRE

Features

- Small deviation of ball neck height after bumping
- Steady bump shape
- No bond pad damage after bonding (LGBE)
- Low deterioration of shear strength in aging test at 200°C (GBC)

Dimensions

Diameter from 15 μm to 38 μm.

TANAKA SILVER ALLOY BONDING WIRE

Ag ALLOY BONDING WIRE

Features

- Reduce material cost with good bondability
- Lower material costs than Gold wire and higher bondability than Copper wire
- High reflectivity in low wavelength range
- Low resistivity (SEB.SEC type)
- Softer FAB (SEC type)

Dimensions

Diameter from 15 μm to 30 μm .



TANAKA COPPER BONDING WIRES

Cu BONDING WIRE

Features

- Enables a reduction in costs with a lower material cost than gold bonding wires
- Excellent reliability
- Wide bonding window
- High and stable bondability

Dimensions

Diameter from 15 ± 1 μm to 500 ± 10 μm .

Cu ALLOY BONDING WIRE

Features

- Higher bond reliability
- Wides bonding window
- Lower resistivity
- Softer FAB

Dimensions

Diameter from 18 μm to 25 μm .



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